Preferred Device

# **High Voltage Transistor** PNP Silicon

## Features

• Pb–Free Packages are Available

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	-150	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-160	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	-500	mAdc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$	P <sub>D</sub>	225	mW
Derate Above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^{\circ}C$	P <sub>D</sub>	300	mW
Derate Above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

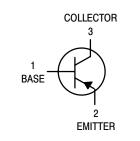
1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

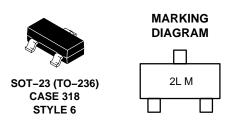
2. Alumina =  $0.4 \times 0.3 \times 0.024$  in 99.5% alumina.



## **ON Semiconductor®**

#### http://onsemi.com





2L = Device Code M = Month Code

IVI	= Month Code	

**ORDERING INFORMATION** 

Device	Package	Shipping <sup>†</sup>
MMBT5401LT1	SOT-23	3000 Tape & Reel
MMBT5401LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT5401LT3	SOT-23	10,000 Tape & Reel
MMBT5401LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

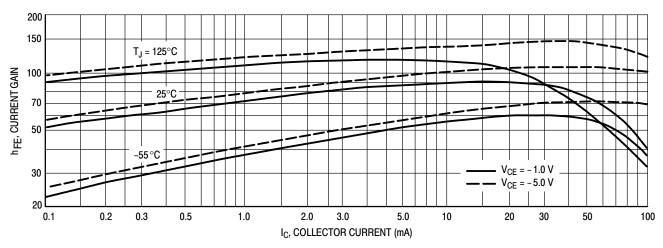
Characteristic		Min	Мах	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage ( $I_C = -1.0 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)CEO</sub>	-150	_	Vdc
Collector – Base Breakdown Voltage ( $I_C = -100 \ \mu Adc, I_E = 0$ )	V <sub>(BR)CBO</sub>	-160	_	Vdc
Emitter – Base Breakdown Voltage ( $I_E = -10 \mu Adc, I_C = 0$ )	V <sub>(BR)EBO</sub>	-5.0	_	Vdc
Collector Cutoff Current $(V_{CB} = -120 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -120 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	I <sub>CES</sub>		-50 -50	nAdc μAdc

#### **ON CHARACTERISTICS**

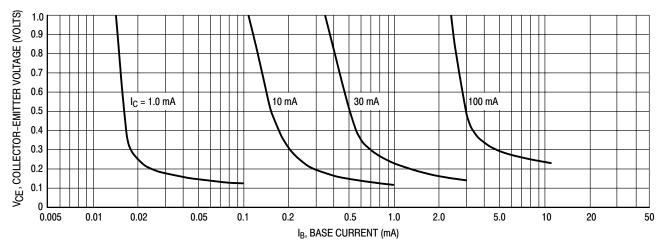
	h <sub>FE</sub>	50 60 50	_ 240 _	-
Collector – Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	-	-0.2 -0.5	Vdc
Base – Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V <sub>BE(sat)</sub>	-	-1.0 -1.0	Vdc

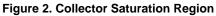
### SMALL-SIGNAL CHARACTERISTICS

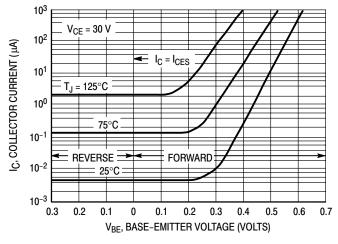
Current-Gain — Bandwidth Product ( $I_C = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	300	MHz
Output Capacitance ( $V_{CB} = -10$ Vdc, $I_E = 0$ , f = 1.0 MHz)	C <sub>obo</sub>	-	6.0	pF
Small Signal Current Gain ( $I_C = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}$ )	h <sub>fe</sub>	40	200	-
Noise Figure (I <sub>C</sub> = -200 $\mu$ Adc, V <sub>CE</sub> = -5.0 Vdc, R <sub>S</sub> = 10 $\Omega$ , f = 1.0 kHz)	NF	-	8.0	dB



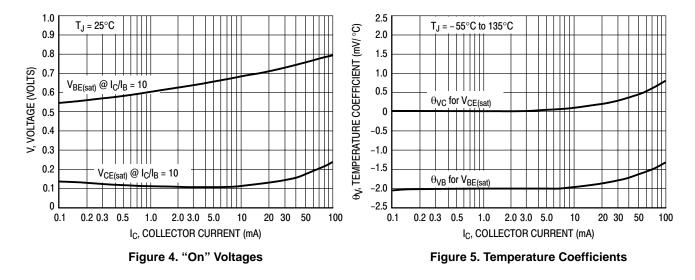












100

70 50

30

20

10

7.0

5.0

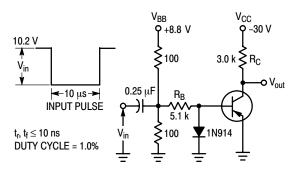
3.0

2.0 1.0

0.2 0.3

0.5 0.7 1.0

C, CAPACITANCE (pF)



Values Shown are for  $I_C @ 10 \mbox{ mA}$ 

Figure 6. Switching Time Test Circuit

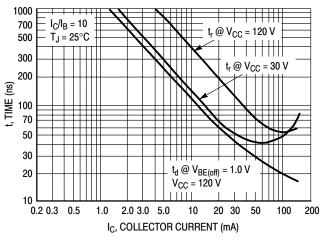


Figure 8. Turn-On Time

Figure 7. Capacitances

2.0 3.0

V<sub>R</sub>, REVERSE VOLTAGE (VOLTS)

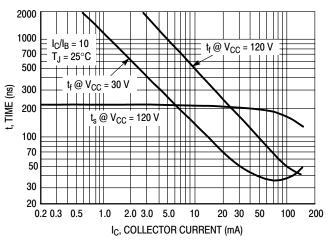
T<sub>.I</sub> = 25°C -

C<sub>obo</sub>

20

5.0 7.0 10

Cibo

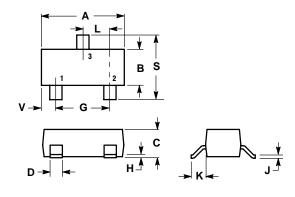




http://onsemi.com 4

#### PACKAGE DIMENSIONS

SOT-23-3 (TO-236) CASE 318-08 **ISSUE AK** 



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. 318–01 THRU –07 AND –09 OBSOLETE, NEW STANDARD 318–08.

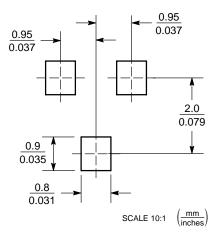
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
в	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
к	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
v	0.0177	0.0236	0.45	0.60

STYLE 6:

PIN 1. BASE 2. EMITTER

3. COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product cult create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agooccide with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent feedesign or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850 ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

#### MMBT5401LT1